

## PMP7207 REV B Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1, C10, C11, C12, C13	5	22uF	GRM32ER71E226KE15L	Murata	Capacitor, Ceramic, 25V, X7R, 15%	1210
C2	1	100pF	Std	TDK	Capacitor, Ceramic, 100-pF, 50-V, X7R, 15%	0603
C3	1	470pF	Std	TDK	Capacitor, Ceramic, 470-pF, 50-V, X7R, 15%	0603
C4	1	8.2nF	Std	TDK	Capacitor, Ceramic, 4700-pF, 50-V, X7R, 15%	0603
C5, C6	2	100nF	Std	TDK	Capacitor, Ceramic, 0.01-uF, 50-V, X7R, 15%, Capacitor, Ceramic, 0.1-uF, 50-V, X7R, 15%	0603
C7	1	220pF	Std	TDK	Capacitor, Ceramic, 33-pF, 50-V, X7R, 15%	0603
C9	1	1.5nF	Std	TDK	Capacitor, Ceramic, 50-V, X7R, 15%	0603
D1	1	SSB44	STD	Vishay	Diode, Schottky, 4-A, 40-V	SMB
J1, J2	2	ED1514	ED1514	OST	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25
L1	1	47 uH	7447709470	Wuerth 1210 series	Inductor, SMT, 3.8Arms, 45.9-milliohms	12mm x 12mm
Q1	1	DMP4050S SS	DMP4050SSS	Diodes (Zetex)	MOSFET, Pch, -40V, -6A, 50-milliohm	SO8
R1	1	0.02	CRCW1206-xxxx-F	Vishay	Resistor, Chip, 1/8W, 1%	1206
R2	1	68.1k	Std	Std	Resistor, Chip, 127K-Ohms, 1/16-W, 1%	0603
R3	1	1.0K	Std	Std	Resistor, Chip, 2.2-Ohms, 1/16-W, 1%	0603
R4	1	10	Std	Std	Resistor, Chip, 0-Ohms, 1/16-W, 1%	0603
R5	1	10k	Std	Std	Resistor, Chip, 100K-Ohms, 1/16-W, 1%	0603
R6	1	1.50K	Std	Std	Resistor, Chip, 1/16-W, 1%	0603
R7	1	6.19k	Std	Std	Resistor, Chip, 26.7K-Ohms, 1/16-W, 1%	0603
R8	1	100k	Std	Std	Resistor, Chip, 100K-Ohms, 1/16-W, 1%	0603
R9	1	49.9	Std	Std	Resistor, Chip, 49.9-Ohms, 1/16-W, 1%	0603
TP1, TP2, TP4, TP7, TP8, TP9, TP10, TP11	8		240-345	Farnell	Test Point, Red, 1mm	0.038
TP5, TP6	2		240-333	Farnell	Test Point, Black, 1mm	0.038
U1	1	TPS40200D	TPS40200D	TI	IC, Low Cost Sync Buck Controller	SO-8

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